

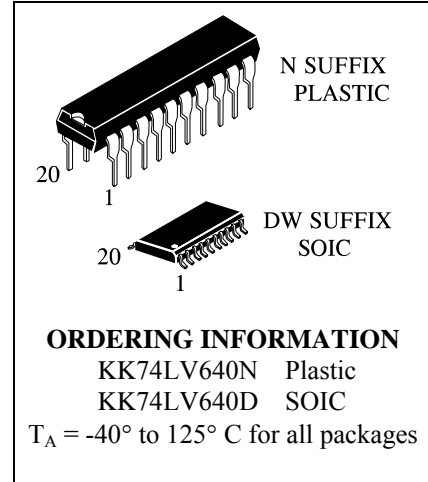
**KK74LV640**

**Octal 3-State Inverting Bus Transceiver**

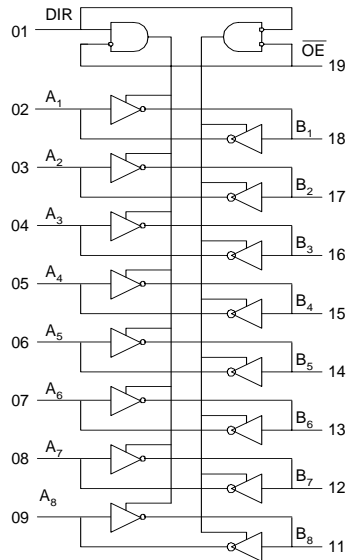
The 74LV640 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT640.

The 74LV640 provides six inverting buffers with Schmitt-trigger action.

- Wide Operating Voltage: 1.2 to 3.6 V
- Optimized for Low Voltage applications: 1.0 to 3.6 V
- Accepts TTL input levels between  $V_{CC}=2.7\text{ V}$  and  $V_{CC}=3.6\text{ V}$
- Low input current

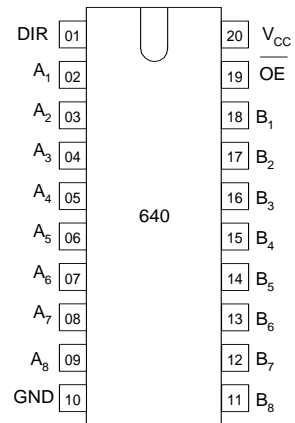


**LOGIC DIAGRAM**



PIN 20= $V_{CC}$   
PIN 10 = GND

**PIN ASSIGNMENT**



**FUNCTION TABLE**

Inputs		Inputs/Outputs	
$\overline{\text{OE}}$	DIR	A	B
L	L	$\overline{\text{A=B}}$	input
L	H	input	$\overline{\text{B=A}}$
H	X	Z	Z

**MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
$V_{CC}$	DC supply voltage (Referenced to GND)	-0.5 ÷ +5.0	V
$I_{IK}^{*1}$	DC input diode current	±20	mA
$I_{OK}^{*2}$	DC output diode current	±50	mA
$I_{O}^{*3}$	DC output source or sink current -bus driver outputs	±35	mA
$I_{GND}$	DC GND current for types with - bus driver outputs	±70	mA
$I_{CC}$	DC $V_{CC}$ current for types with - bus driver outputs	±70	mA
$P_D$	Power dissipation per package, plastic DIP+ SOIC package+	750 500	mW
$T_{stg}$	Storage temperature	-65 ÷ +150	°C
$T_L$	Lead temperature, 1.5 mm from Case for 10 seconds (Plastic DIP ), 0.3 mm (SOIC Package)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur.  
Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 12 mW/°C from 65° to 125°C

SOIC Package: : - 8 mW/°C from 65° to 125°C

\*<sup>1</sup>:  $V_I < -0.5V$  or  $V_I > V_{CC}+0.5V$

\*<sup>2</sup>:  $V_O < -0.5V$  or  $V_O > V_{CC}+0.5V$

\*<sup>3</sup>:  $-0.5V < V_O < V_{CC}+0.5V$

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)	1.2	3.6	V
$V_{IN}, V_{OUT}$	DC Input Voltage (Referenced to GND)	0	$V_{CC}$	V
$T_A$	Operating Temperature, All Package Types	-40	+125	°C
$t_{LH}, t_{HL}$	Input Rise and Fall Time	0	1000 700 500 400	ns
	$V_{CC} = 1.2 V$			
	$V_{CC} = 2.0 V$			
	$V_{CC} = 3.0 V$			
	$V_{CC} = 3.6 V$			

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{IN}$  and  $V_{OUT}$  should be constrained to the range  $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

**DC ELECTRICAL CHARACTERISTICS** (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit						Unit
				25°C		-40°C ÷ 85°C		-40°C ÷ 125°C		
				min	max	min	max	min	max	
V <sub>IH</sub>	High-Level Input Voltage	V <sub>O</sub> = V <sub>CC</sub> - 0.1 V	1.2	0.9	-	0.9	-	0.9	-	V
			2.0	1.4	-	1.4	-	1.4	-	
			3.0	2.1	-	2.1	-	2.1	-	
			3.6	2.5	-	2.5	-	2.5	-	
V <sub>IL</sub>	Low -Level Input Voltage		1.2	-	0.3	-	0.3	-	0.3	V
			2.0	-	0.6	-	0.6	-	0.6	
			3.0	-	0.9	-	0.9	-	0.9	
			3.6	-	1.1	-	1.1	-	1.1	
V <sub>OH</sub>	High-Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> - or V <sub>IL</sub> I <sub>O</sub> = -50 μA	1.2	1.1	-	1.0	-	1.0	-	V
			2.0	1.92	-	1.9	-	1.9	-	
			3.0	2.92	-	2.9	-	2.9	-	
			3.6	3.52	-	3.5	-	3.5	-	
		V <sub>I</sub> = V <sub>IH</sub> - or V <sub>IL</sub> I <sub>O</sub> = -8.0 mA	3.0	2.48	-	2.34	-	2.20	-	
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> - or V <sub>IL</sub> I <sub>O</sub> = 50 μA	1.2	-	0.09	-	0.1	-	0.1	V
			2.0	-	0.09	-	0.1	-	0.1	
			3.0	-	0.09	-	0.1	-	0.1	
			3.6	-	0.09	-	0.09	-	0.09	
		V <sub>I</sub> = V <sub>IH</sub> - or V <sub>IL</sub> I <sub>O</sub> = 8.0 mA	3.0	-	0.33	-	0.40	-	0.50	
I <sub>IL</sub>	Low-Level Input Leakage Current	V <sub>I</sub> = 0 V	*	-	-0.1	-	-1.0	-	-1.0	μA
I <sub>IH</sub>	High-Level Input Leakage Current	V <sub>I</sub> = V <sub>CC</sub>	*	-	0.1	-	1.0	-	1.0	μA
I <sub>OZ</sub>	Maximum Three-State Leakage Current	V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	1.2 *	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	Quiescent Supply Current (per Package)	V <sub>I</sub> = 0 V or V <sub>CC</sub> I <sub>O</sub> = 0 μA	*	-	8.0	-	80.0	-	180.0	μA

**AC ELECTRICAL CHARACTERISTICS** ( $C_L=50\text{ pF}$ ,  $t_{LH}=t_{HL}=6.0\text{ ns}$ ,  $R_L=1\text{ k}\Omega$ )

Symbol	Parameter	Test Conditions	$V_{CC}$ V	Guaranteed Limit						Unit
				25°C		-40°C ÷ 85°C		-40°C ÷ 125°C		
				min	max	min	max	min	max	
$t_{PLH}$ , $t_{PHL}$	Propagation Delay, A to B, B to A	$V_{IL}=0\text{ V}$ $V_{IH}=V_{CC}$ $t_{LH}=t_{HL}=6.0\text{ ns}$ $C_L=50\text{ pF}$	1.2 2.0 *	- 100 23 14	- 23 18	- 125 28 18	- 140 34 21	- 140 34 21	ns	
$t_{PLZ}$ , $t_{PHZ}$	Propagation Delay, Direction or Output Enable to A or B	$V_{IL}=0\text{ V}$ $V_{IH}=V_{CC}$ $t_{LH}=t_{HL}=6.0\text{ ns}$ $C_L=50\text{ pF}$	1.2 2.0 *	- 120 30 20	- 140 37 24	- 140 37 24	- 160 43 28	- 160 43 28	ns	
$t_{PZL}$ , $t_{PZH}$	Propagation Delay, Direction or Output Enable to A or B	$V_{IL}=0\text{ V}$ $V_{IH}=V_{CC}$ $t_{LH}=t_{HL}=6.0\text{ ns}$ $C_L=50\text{ pF}$	1.2 2.0 *	- 120 28 17	- 140 35 21	- 140 35 21	- 160 43 26	- 160 43 26	ns	
$t_{TLH}$ , $t_{THL}$	Output Transition Time, Any Output	$V_{IL}=0\text{ V}$ $V_{IH}=V_{CC}$ $t_{LH}=t_{HL}=6.0\text{ ns}$ $C_L=50\text{ pF}$	1.2 2.0 *	- 60 16 10	- 75 20 13	- 75 20 13	- 90 24 15	- 90 24 15	ns	
$C_I$	Input Capacitance (Pin 1 or Pin 19)		3.0	-	7.0	-	-	-	-	pF
$C_{IO}$	Input Capacitance (Pin 2-9 or Pin 11-18)		3.0	-	20.0	-	-	-	-	pF
$C_{PD}$		$V_I=0\text{ V}$ or $V_{CC}$		-	50	-	-	-	-	pF

\* -  $V_{CC}=3.3\pm 0.3\text{ V}$

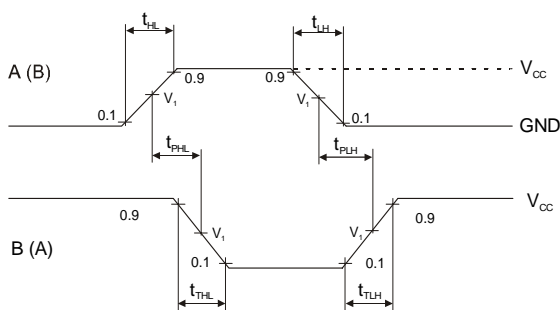
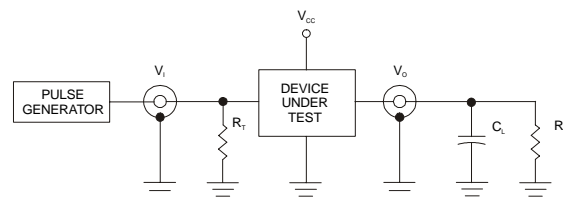


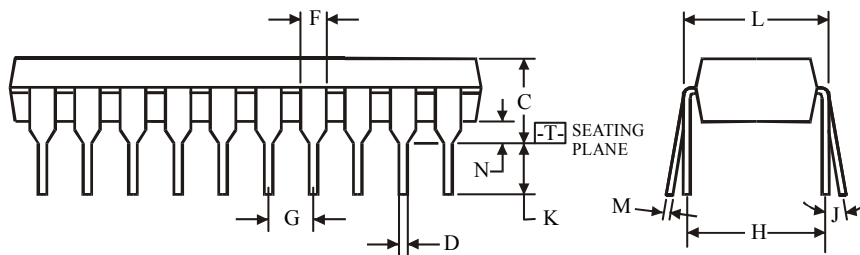
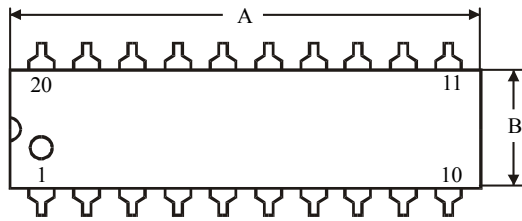
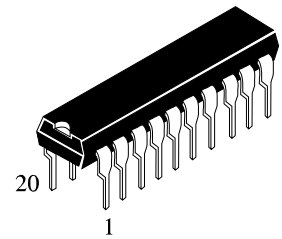
Figure 1. Switching Waveforms



Termination resistance  $R_T$  – should be equal to  $Z_{OUT}$  of pulse generators

Figure 2. Test Circuit

**N SUFFIX PLASTIC DIP  
(MS - 001AD)**



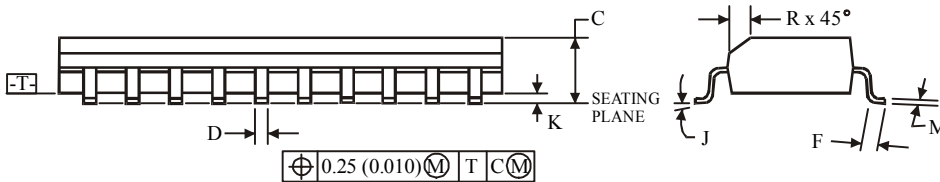
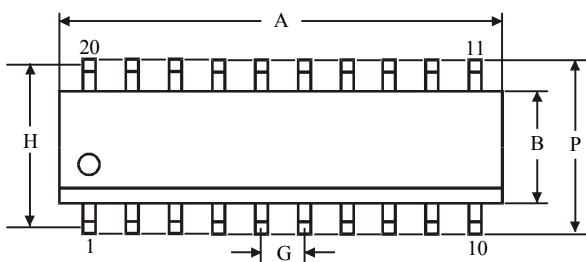
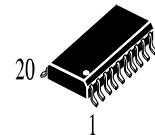
$\oplus 0.25 (0.010) \text{M} \text{T}$

**NOTES:**

- Dimensions "A", "B" do not include mold flash or protrusions.  
Maximum mold flash or protrusions 0.25 mm (0.010) per side.

Symbol	Dimension, mm	
	MIN	MAX
A	24.89	26.92
B	6.1	7.11
C		5.33
D	0.36	0.56
F	1.14	1.78
G	2.54	
H	7.62	
J	0°	10°
K	2.92	3.81
L	7.62	8.26
M	0.2	0.36
N	0.38	

**D SUFFIX SOIC  
(MS - 013AC)**



$\oplus 0.25 (0.010) \text{M} \text{T} \text{C} \text{M}$

**NOTES:**

- Dimensions A and B do not include mold flash or protrusion.
- Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B - 0.25 mm (0.010) per side.

Symbol	Dimension, mm	
	MIN	MAX
A	12.6	13
B	7.4	7.6
C	2.35	2.65
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	9.53	
J	0°	8°
K	0.1	0.3
M	0.23	0.32
P	10	10.65
R	0.25	0.75